

3.4mm RIGHT ANGLE LED INDICATOR

Part Number: L-1384AD/1SRD

Super Bright Red

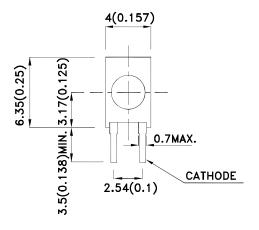
Features

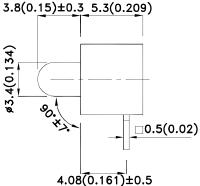
- Ideal for card edge status indication.
- Wide viewing angle.
- High reliability-life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions









- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
L-1384AD/1SRD	Super Bright Red (GaAlAs)	Red Diffused	150	300	60°
		Rea Diliasea	*40	*90	

Notes:

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.		Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Super Bright Red	660	*655		nm	IF=20mA	
λD [1]	Dominant Wavelength	Super Bright Red	640	*640		nm	IF=20mA	
Δλ1/2	Spectral Line Half-width	Super Bright Red	20			nm	IF=20mA	
С	Capacitance	Super Bright Red	45			pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Super Bright Red	1.85		2.5	V	IF=20mA	
lr	Reverse Current	Super Bright Red			10	uA	V _R = 5V	

- 1.Wavelength: +/-1nm.

Absolute Maximum Ratings at TA=25°C

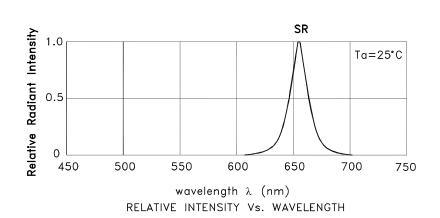
Parameter	Super Bright Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	155	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
 5mm below package base.

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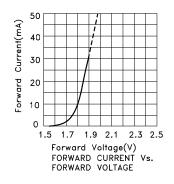
Luminous intensity/ luminous Flux: +/-15%.
 *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

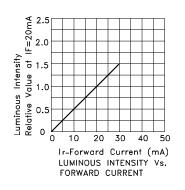
Forward Voltage: +/-0.1V.
 *Wavelength value is traceable to the CIE127-2007 compliant national standards.

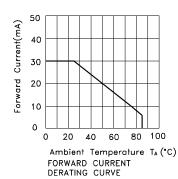


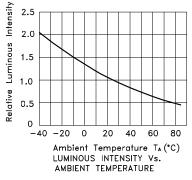
Super Bright Red

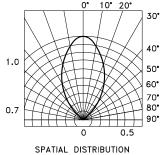
L-1384AD/1SRD





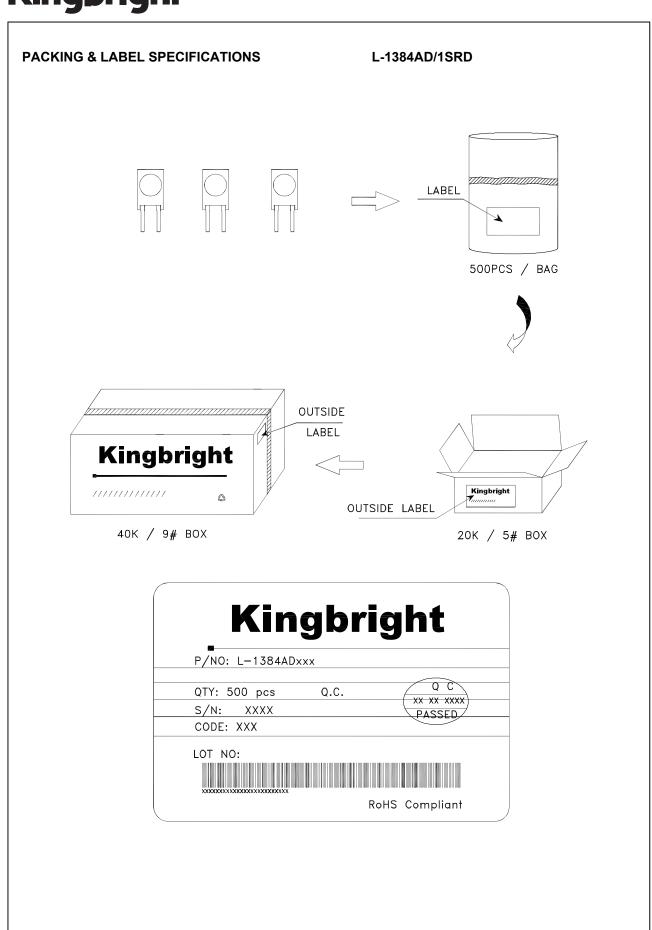






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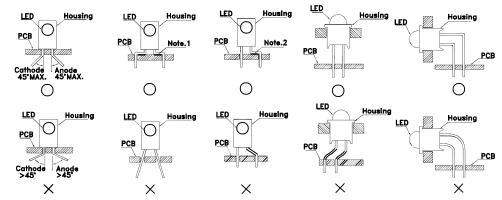
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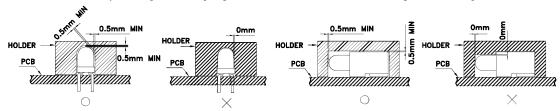
PRECAUTIONS

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

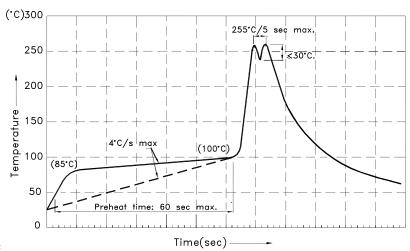


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

2.Peak wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

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